

曜凌光電股份有限公司

住址: 42878 台中市大雅区科雅路 25 號 5F WEB: http://www.Raystar-Optronics.com
5F., No.25, Keya Rd., Daya Dist., Taichung E-mail: sales@raystar-optronics.com
City 428, Taiwan Tel:886-4-2565-0761 Fax: 886-4-2565-0760

RX12864B-BIW

SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:



Revision History

VERSION	DATE	REVISED PAGE NO.	Note
0	2012/11/28		First issue
Α	2014/07/22		Remove IC
			information



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1.General Specification

The Features is described as follow:

■ Module dimension: 89.7x 49.8 x12.1 (max.) mm

■ View area: 69.0 x 36.5 mm

Active area: 63.97 x31.97 mm

■ Number of dots: 128 x 64

■ Dot size: 0.47 x0.47 mm

■ Dot pitch: 0.5 x 0.5 mm

■ LCD type: STN Negative, Blue Transmissive

■ Duty: 1/65 , 1/9 Bias

■ View direction: 6 o'clock

■ Backlight Type: LED, White

■ IC: ST7565P



2. Module Classification Information

<u>R</u>	<u>X</u>	<u>12864</u>	<u>B</u>	_	<u>B</u>	<u>I</u>	<u>W</u>
①	2	3	4	_	(5)	6	7

Item	Description						
1	R : Raystar Optronics Inc.						
2	Display	C: Character Type,		T:TAB Type			
	ыѕріау	G: Graphic Type		X:COG Type			
3	Display Font :						
4	Serials code :						
		P→TN Positive, Gray		V→FSTN Ne	egative, Blue		
		N→TN Negative,		T→FSTN Ne	egative, Black		
		L→VA Negative			egative (Double film)		
		H→ HTN Positive, Gray		F→FSTN Po			
5	LCD	I→HTN Negative, Black		K→FSC Neg			
		U→HTN Negative, Blue		S→FSC Pos			
		B→STN Negative, Blue			gative, Black		
		G→STN Positive, Gray		C→CSTN Negative, Black			
		Y→STN Positive, Yellow	Green	A→ASTN Negative, Black			
	Polarizer	A: Reflective, N.T, 6:00		K: Transflective, W.T,12:00			
	Type,	D: Reflective, N.T, 12:0		1 : Transflective, U.T,6:00			
	турс,	G: Reflective, W. T, 6:00			etive, U.T.12:00		
6	Temperature	J: Reflective, W. T, 12:0			ssive, N.T,6:00		
	range,	0 : Reflective, U. T, 6:00			ssive, N.T,12:00		
	\	3 : Reflective, U. T, 12:0 B : Transflective, N.T,6:0			sive, W. T, 6:00 sive, W.T,12:00		
	View direction	E: Transflective, N.T.12			ssive, W. 1, 12.00		
	direction	H: Transflective, W.T,6:			ssive, U.T,12:00		
		N→ Without backlight	W→LE[H→LED, High light White		
		P→EL, Blue	A→LED		S→LED, Full color		
		T→EL, Green	R→LED	•	J→DIP LED, Blue		
7	De ablicate	D→EL, White), Orange	K→DIP LED, White		
7	Backlight	M→EL, Yellow Green	B→LED	· •	E→DIP LED, Yellow		
	7 (F→CCFL, White		, Dual color	L→DIP LED, Amber		
		Y→LED, Yellow Green		, Full color	I→DIP LED, Red		
		G→LED, Green					



3.Interface Pin Function

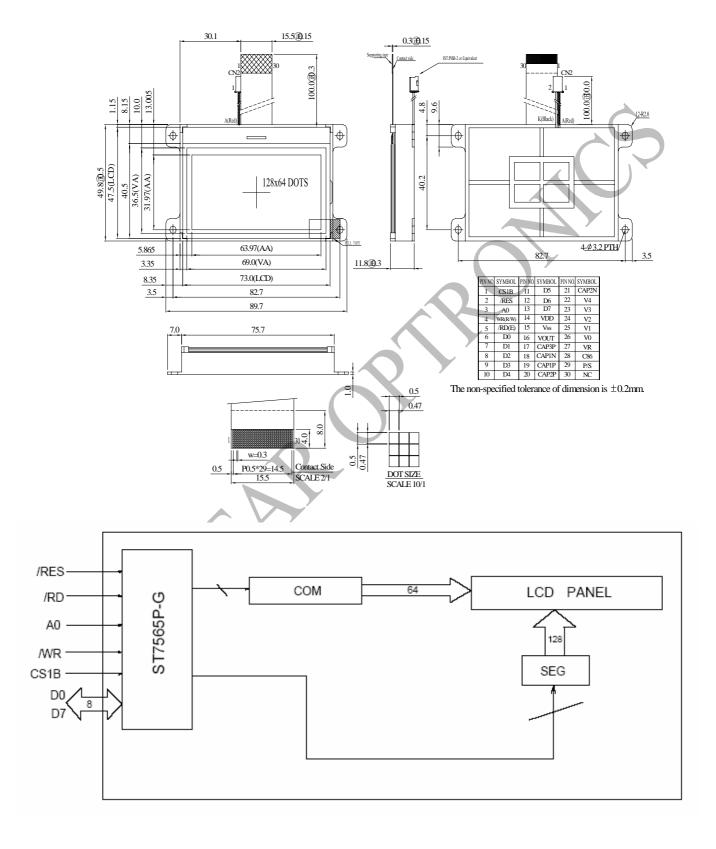
Pin No.	Symbol	I/O	Description
1	/CS1B	I	This is the chip select signal.
2	/RES	I	When RES is set to "L", the setting are initialized.
3	A0	I	This is connect to the least significant bit of the normal MPU address bus, and it determines whether the data bits are data or command. A0 = "H": Indicates that D0 to D7 are display data. A0 = "L": Indicates that D0 to D7 are control data.
4	/WR(R/W)	I	 When connected to 8080 series MPU, this pin is treated as the "/WR" signal of the 8080 MPU and is LOW-active. The signals on the data bus are latched at the rising edge of the /WR signal. When connected to 6800 series MPU, this pin is treated as the "R/W" signal of the 6800 MPU and decides the access type: When R/W = "H": Read. When R/W = "L": Write.
5	/RD(E)		 When connected to 8080 series MPU, this pin is treated as the "/RD" signal of the 8080 MPU and is LOW-active. The data bus is in an output status when this signal is "L". When connected to 6800 series MPU, this pin is treated as the "E" signal of the 6800 MPU and is HIGH-active. This is the enable clock input terminal of the 6800 Series MPU.
6~13	D0~ D7	I/O	Data bus line
14	VDD	Power Supply	Power supply
15	VSS	Power Supply	Ground
16	VOUT	0	DC/DC voltage converter. Connect a capacitor between this terminal and vss or VDD
17	CAP3P	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.
18	CAP1N	0	DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1P terminal.



19	CAP1P	0		DC/DC voltage converter. Connect a capacitor between this terminal and the CAP1N terminal.					
20	CAP2P	0		voltage conve		•	citor betwee	n:	
21	CAP2N	0		voltage conve		•	citor betwee	n	
22~26	V4~ V0	Power Supply		a multi-level po	wer supp	ly for the li	quid crystal		
27	VR	І	Output v betweer IRS = "L not used	Output voltage regulator terminal. Provides the voltage between VSS and V0 through a resistive voltage divider. IRS = "L": the V0 voltage regulator internal resistors are not used. IRS = "H": the V0 voltage regulator internal resistors are					
28	C86	I	C86 = "I	This is the MPU interface selection pin. C86 = "H": 6800 Series MPU interface. C86 = "L": 8080 Series MPU interface					
29	P/S		terminal P/S = "F P/S = "L	he parallel data I": Parallel data ": Serial data in owing applies d Data/Command A0 A0	input.	on the P/S			
			When P/S = "L", D0 to D5 fixed "H". /RD (E) and /WR (R/W) are fixed to either "H" or "L". With serial data input, It is impossible read data from RAM						
30	NC	-	No conr	nection.					



4.Contour Drawing &Block Diagram



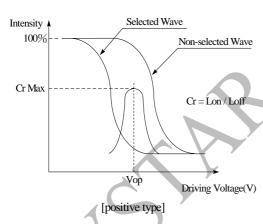


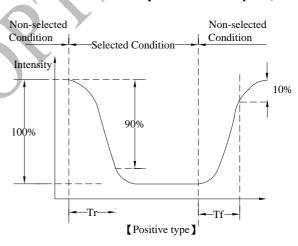
5.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	20	ψ= 180°
Viou Anglo	θ	CR≧2	0	_	40	ψ= 0°
View Angle	θ	CR≧2	0	_	30	ψ= 90°
	θ	CR≧2	0	_	30	ψ= 270°
Contrast Ratio	CR	_	_	3	7	_
Response Time	T rise	_	_	200	300	ms
	T fall	_	Q	250	350	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



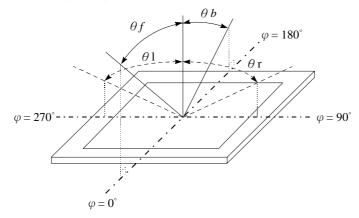


Conditions:

Operating Voltage : Vop Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≥2)





6.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T _{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T _{ST}	-30	_	+80	$^{\circ}$ C
Power Supply Voltage	VDD	-0.3	_	3.6	Y
Power supply voltage (VDD standard)	V0, VOUT	-0.3	-	14.5	V
Power supply voltage (VDD standard)	V1, V2, V3, V4	-0.3		V0+0.3	٧



7. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_	2.7	_	3.3	V
		Ta=-20°ℂ	9.5	9.8	10.5	V
Supply Voltage For LCM	Vo-V _{SS}	Ta=25°C	9.2	9.45	9.7	V
		Ta=70°C	8.95	9.2	9.45	V
Input High Volt.	V_{IH}	_	0.8 V _{DD}	7	V_{DD}	V
Input Low Volt.	V _{IL}	_	Vss	_	0.2 V _{DD}	V
Output High Volt.	V _{OH}	I _{OUT} =-0.5mA	0.8 V _{DD}))	V_{DD}	V
Output Low Volt.	V _{OL}	I _{OUT} =0.5mA	Vss	/ _	0.2V _{DD}	V
Supply Current(No		N	7			
include	I_{DD}	(-) >	-	0.60	2.0	mA
LED Backlight)						

NOTE 1: 1) Duty ratio=1/65, Bias=1/9

2) Measured in Dots ON-state

NOTE 2: Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance



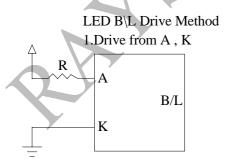
8.Backlight Information

Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	61.2	72	100	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	4
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	600	800	-	CD/M ²	ILED=72mA
Waya Langth	Х	0.27	0.3	0.33	V	ILED=72mA
Wave Length	Υ	0.26	0.29	0.32	, ,	ILED=72IIIA
LED Life Time	_	_	50000	-	Hr.	ILED≦72 mA 25℃,50-60%RH
Color	White					23 (,50-00 /61(11

Note: The LED of B/L is drive by current only; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note1:50K hours is only an estimate for reference.





9.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°ℂ 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



10.Inspection specification

NO	Item	Criterion				AQL	
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, s defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 			pecifications.	0.65	
02	Black or white spots on LCD	three white o	-	on display ≤ 0.25 ots present.	mm, no more than	2.5	
	(display only)	2.2 Densely spaced: No more than two spots or lines within 3mm					
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : $\Phi = (x + y) / 2$ $X \longrightarrow X$ 3.2 Line type : A	2 1 Y	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Acceptable Q TY Accept no dense 2 As round type	2.5	
04	Polarizer bubbles	If bubbles are visible judge using black specifications, not to find, must che specify direction	k spot ot easy eck in	Size Φ $\Phi \le 0.20$ $0.20 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5	



NO	Item	Criterion A			AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
		Symbols Define: x: Chip length y: k: Seal width t: C L: Electrode pad length 6.1 General glass chip	Chip width z: Chip Glass thickness a: LCE	thickness O side length	
06	Chipped glass	z: Chip thickness $Z \leq 1/2t$ $1/2t < z \leq 2t$	y: Chip width Not over viewing area Not exceed 1/3k	x: Chip length x≤1/8a x≤1/8a	2.5
		6.1.2 Corner crack:	chips, x is total length of	y	
?		z: Chip thickness Z≦1/2t	y: Chip width Not over viewing area	x: Chip length x≦1/8a	
		1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a	
		⊙If there are 2 or more	chips, x is the total leng	gth of each chip.	



NO	Item	Criterion	AQL		
		Symbols:			
		x: Chip length y: Chip width z: Chip thickness			
		k: Seal width t: Glass thickness a: LCD side length			
		L: Electrode pad length			
		6.2 Protrusion over terminal :			
		6.2.1 Chip on electrode pad :			
		Z Z			
		v: Chin width v: Chin longth 7: Chin thickness			
		y: Chip width x: Chip length z: Chip thickness $y \le 0.5$ mm $x \le 1/8$ a $0 < z \le t$			
		6.2.2 Non-conductive portion:			
06	Glass crack	y Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z Z	2.5		
		y: Chip width x: Chip length z: Chip thickness			
		$y \le L$ $x \le 1/8a$ $0 < z \le t$			
		⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO			
		must remain and be inspected according to electrode terminal			
		specifications.			
		•			
		⊙ If the product will be heat sealed by the customer, the alignment			
X		mark not be damaged. 6.2.3 Substrate protuberance and internal crack.			
		v.2.3 Substrate protuberance and internal crack.			
		y: width x: length			
		y≤1/3L x ≤ a			
		у			
		(*)			



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	2.5
		indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the	0.65
		seal area on the PCB. And there should be no more than three places.	2.5
		10.5 No oxidation or contamination PCB terminals.	
10	PCB · COB	10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.	2.5 0.65
		10.7 The jumper on the PCB should conform to the product	
	10	characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.	0.65
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5
Q		X * Y<=2mm2	2.5
		11.1 No un-melted solder paste may be present on the PCB.	2.5
11	Soldering	11.2 No cold solder joints, missing solder connections, oxidation or icicle.	2.5
	Coldoning	11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65



NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
12	General	pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip	2.5
	appearance	component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on	
		packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	



11.Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)



12. Material List of Components for RoHs

1. RAYSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS						

Above limited value is set up according to RoHS.

2.Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°€;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.



13. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.





Page: 1

		i agc.			
	LCM Sample	Estimate Feedback Sheet			
Module Number :					
1 · Panel Specification :					
1. Panel Type:	□ Pass	□ NG ,			
2. View Direction:	□ Pass	□ NG ,			
3. Numbers of Dots:	□ Pass	□ NG ,			
4. View Area:	□ Pass	□ NG ,			
5. Active Area:	□ Pass	□ NG ,			
6.Operating Temperature:	□ Pass	□ NG ,			
7.Storage Temperature:	□ Pass	□ NG ,			
8.Others:					
2 · Mechanical Specification :					
1. PCB Size :	□ Pass	□ NG ,			
2.Frame Size :	□ Pass	□ NG ,			
3.Materal of Frame :	□ Pass	□ NG ,			
4.Connector Position:	□ Pass	□ NG ,			
5.Fix Hole Position:	□ Pass	□ NG ,			
6.Backlight Position:	□ Pass	□ NG ,			
7. Thickness of PCB:	□ Pass	□ NG ,			
8. Height of Frame to PCB:	□ Pass	□ NG ,			
9.Height of Module:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
3 · Relative Hole Size :		7			
1.Pitch of Connector:	□ Pass	□ NG ,			
2.Hole size of Connector:	□ Pass	□ NG ,			
3.Mounting Hole size :	□ Pass	□ NG ,			
4.Mounting Hole Type:	□ Pass	□ NG ,			
5.Others:	□ Pass	□ NG ,			
4 · Backlight Specification :					
1.B/L Type:	□ Pass	□ NG ,			
2.B/L Color:	□ Pass	□ NG ,			
3.B/L Driving Voltage (Referen	pe) : □ Pass □ NG ,				
4.B/L Driving Current:	□ Pass	□ NG ,			
5.Brightness of B/L:	□ Pass	□ NG ,			
6.B/L Solder Method:	□ Pass	□ NG ,			
7.Others:	□ Pass	□ NG ,			

>> Go to page 2 <<



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Module Number :					
5 · Electronic Characteristics of Module :					
1.Input Voltage :	□ Pass	□ NG ,			
2.Supply Current:	□ Pass	□ NG ,			
3.Driving Voltage for LCD:	□ Pass	□ NG ,			
4.Contrast for LCD:	□ Pass	□ NG ,			
5.B/L Driving Method:	□ Pass	□ NG ,			
6.Negative Voltage Output:	□ Pass	□ NG ,			
7.Interface Function:	□ Pass	□ NG ,			
8.LCD Uniformity:	□ Pass	□ NG ,			
9.ESD test:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
6 · Summary :					
Sales signature:					
		- Data: / /			
Customer Signature : <u>Date : / / _</u>					